MA2C700 (MA700), MA2C700A (MA700A)

Silicon epitaxial planar type

For wave detection

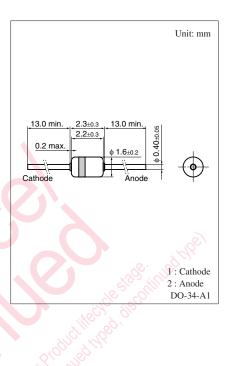
For super high speed switching

Features

- \bullet Low forward voltage V_F and good wave detection efficiency η
- Small temperature coefficient of forward characteristic
- Small reverse current I_R
- High-density mounting (5 mm pitch insertion) is possible

Parameter		Symbol	Rating	Unit			
Reverse voltage	MA2C700	V _R	15	V			
	MA2C700A		30				
Maximum peak	MA2C700	V _{RM}	15	V			
reverse voltage	MA2C700A		30				
Forward current		$I_{\rm F}$	30	mA			
Peak forward current		I _{FM}	150	mA			
Junction temperature		Tj	125	°C			
Storage temperature		T _{stg}	-55 to +125	°C			

Absolute Maximum Ratings $T_a = 25^{\circ}C$

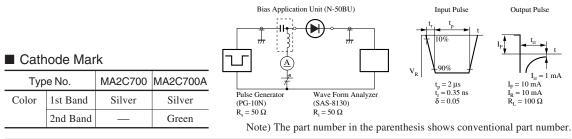


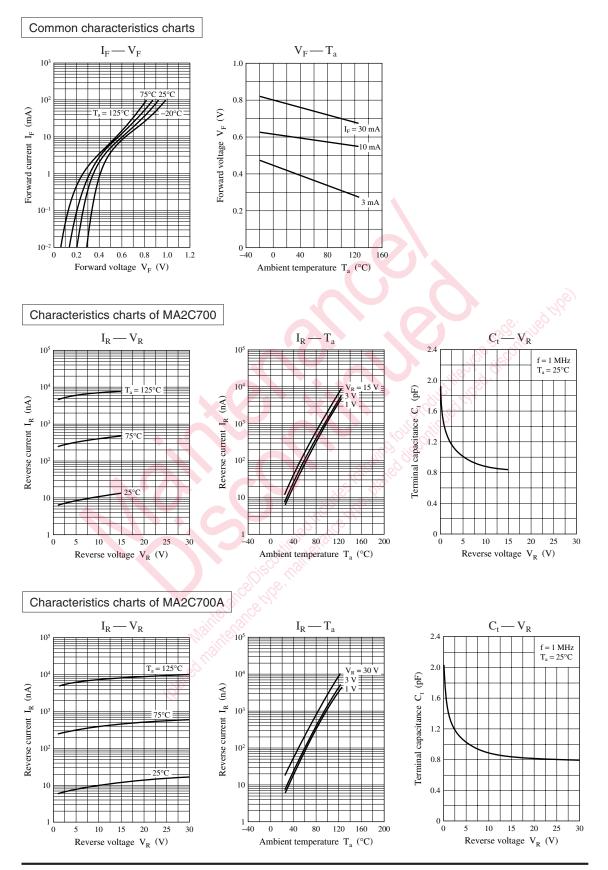
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Paramete	er	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage		V _{F1}	$I_F = 1 \text{ mA}$			0.4	V
		V _{F2}	$I_F = 30 \text{ mA}$			1.0	
Reverse current	MA2C700	I _R	V _R = 15 V			100	nA
	MA2C700A		$V_R = 30 V$			150	
Terminal capacitance		C _t	$V_R = 1 V, f = 1 MHz$		1.3		pF
Reverse recovery time	e *	t _{rr}	$I_F = I_R = 10 \text{ mA}$		1.0		ns
		AN AN A	$I_{\rm rr} = 1 \text{ mA}, R_{\rm L} = 100 \Omega$				
Detection efficiency	MA2C700	No nor	$V_{IN} = 3 V_{(peak)}$, f = 30 MHz		65		%
	MA2C700A		$R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$		60		

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 2 GHz. $4.*: t_{rr}$ measurement circuit





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